

功能

- 带金属盖的微型陶瓷表面贴装
- 提供三态功能
- 供电范围：1.62V~3.63V(兼容1.8V, 2.5V, 3.3V)
- 封装尺寸:3.2×2.5×1.0mm
- 符合RoHS, 无铅和无卤素标准。

应用

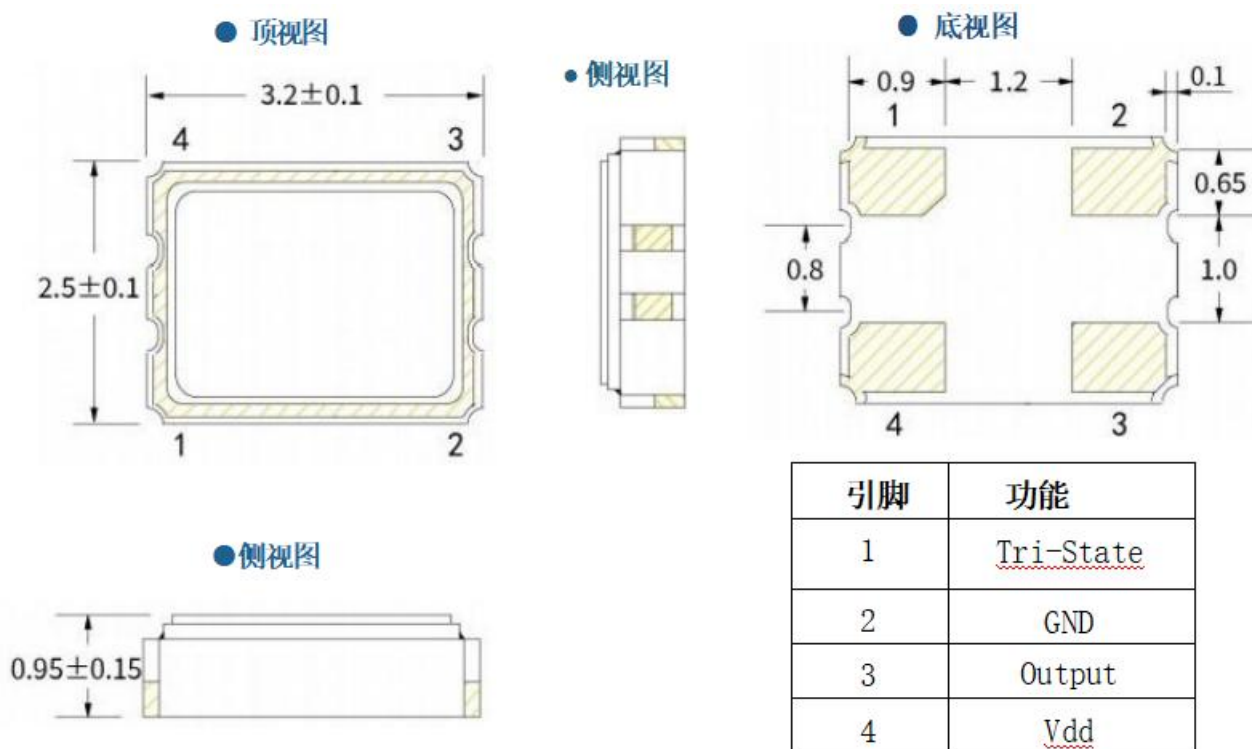
- 无线设备
- 物联网 (IOT) 设备
- 以太网/千兆以太网
- 音频, 视频, 游戏产品
- 微型基站



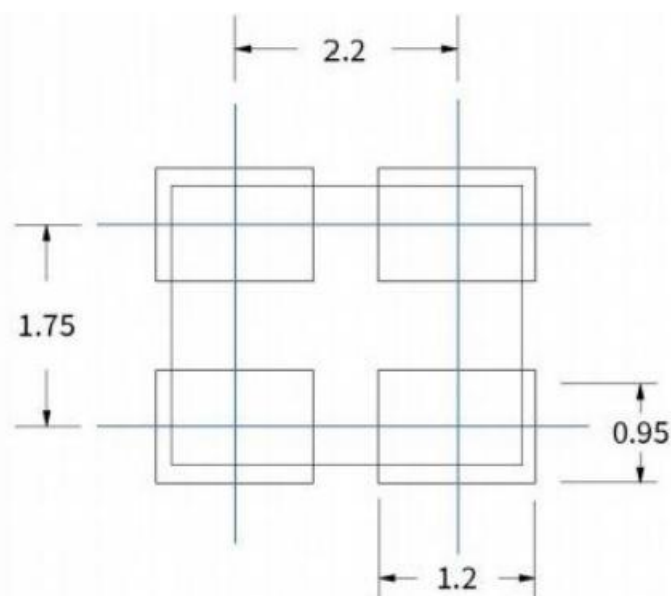
电气规格

项目	符号	最小值	标准值	最大值	单位	备注
频率范围	Freq	1.000		54	MHZ	
工作温度	T_use	-20		70	°C	±20ppm
		-40		85	°C	±30ppm
储存温度	T_stg	-55		125	°C	
电源电压	Vdd	1.62		3.63	v	
输出负载	L_CMOS		15		pf	
消耗电流	ICC			10	mA	1MHz≤Freq.<40MHz
				20		40MHz≤Freq.≤54MHz
占空比	SYM	45		55	%	50 %Vdd level,L_CMOS≤15pF
上升/下降时间	TR/TF			5	ns	10%vdd to 90%Level
启动时间	T_str			5	ms	To 90%of Final Amplitude
输出电压	VoH	0.9Vdd				
	VoL			0.1Vdd	v	
使能高电平	VIH	0.7VDD			v	输出使能OE是高电平1或者悬空, 频率输出; 输出 使能OE是低电平0, 则无频率输出。
使能低电平	VIL			0.3VDD	v	
年老化	f_age			±3	ppm	1st. Year at 25℃

产品尺寸 (UNIT:mm)

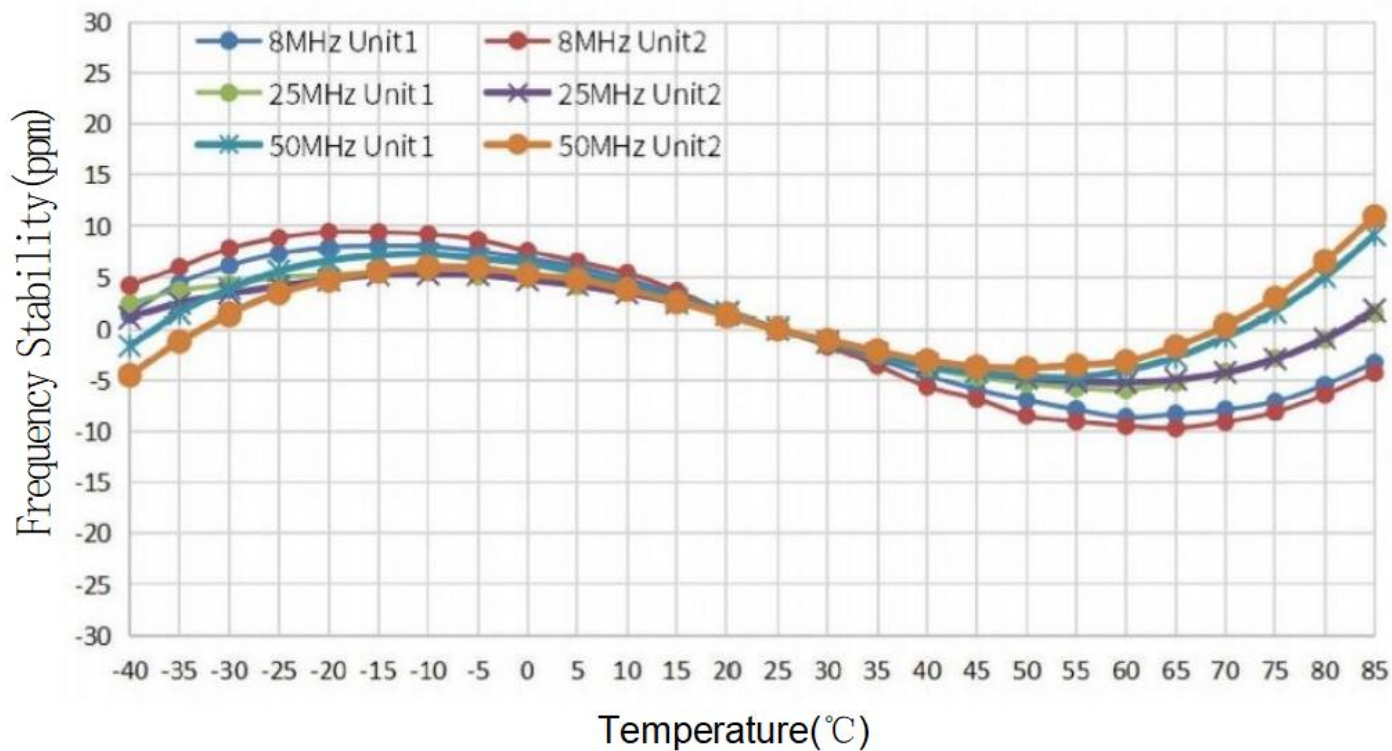


焊盘布局 (UNIT:mm)



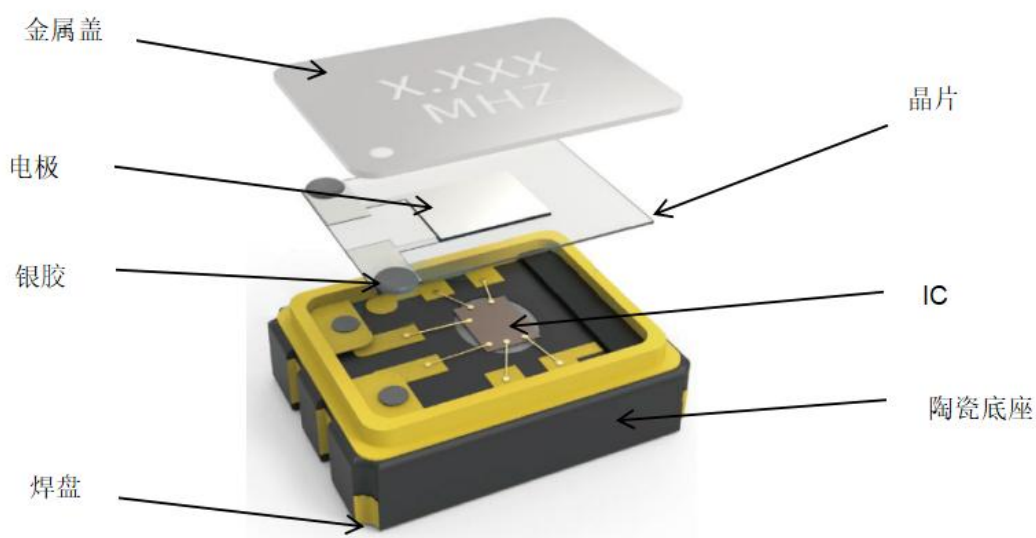
频率温度特性

频率稳定性与温度变化 (3225)

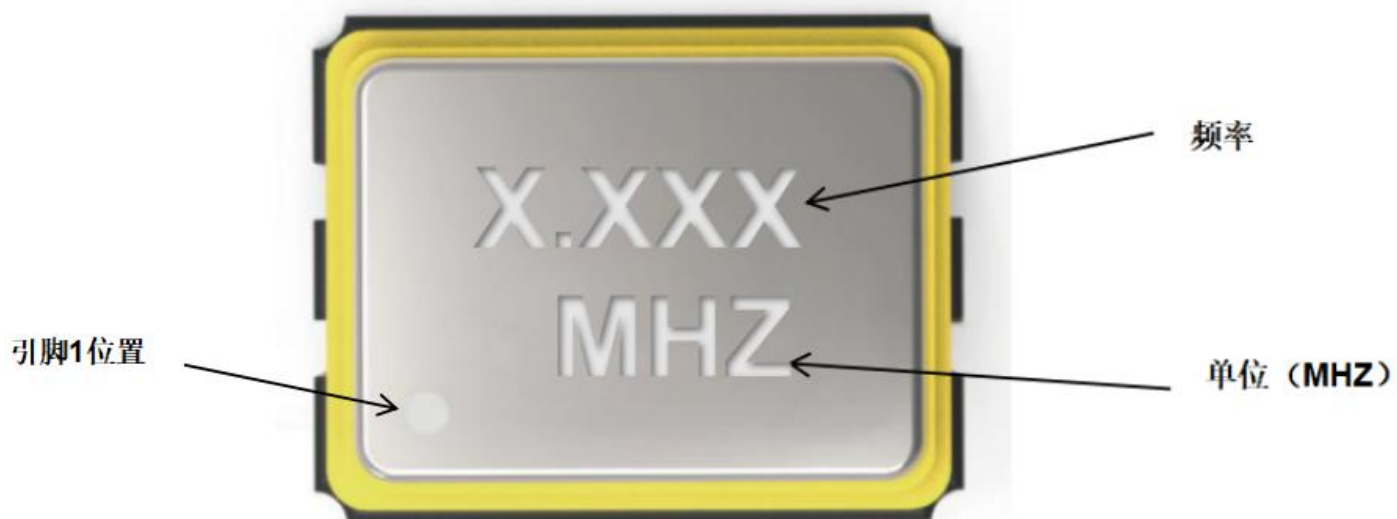


产品结构与印字

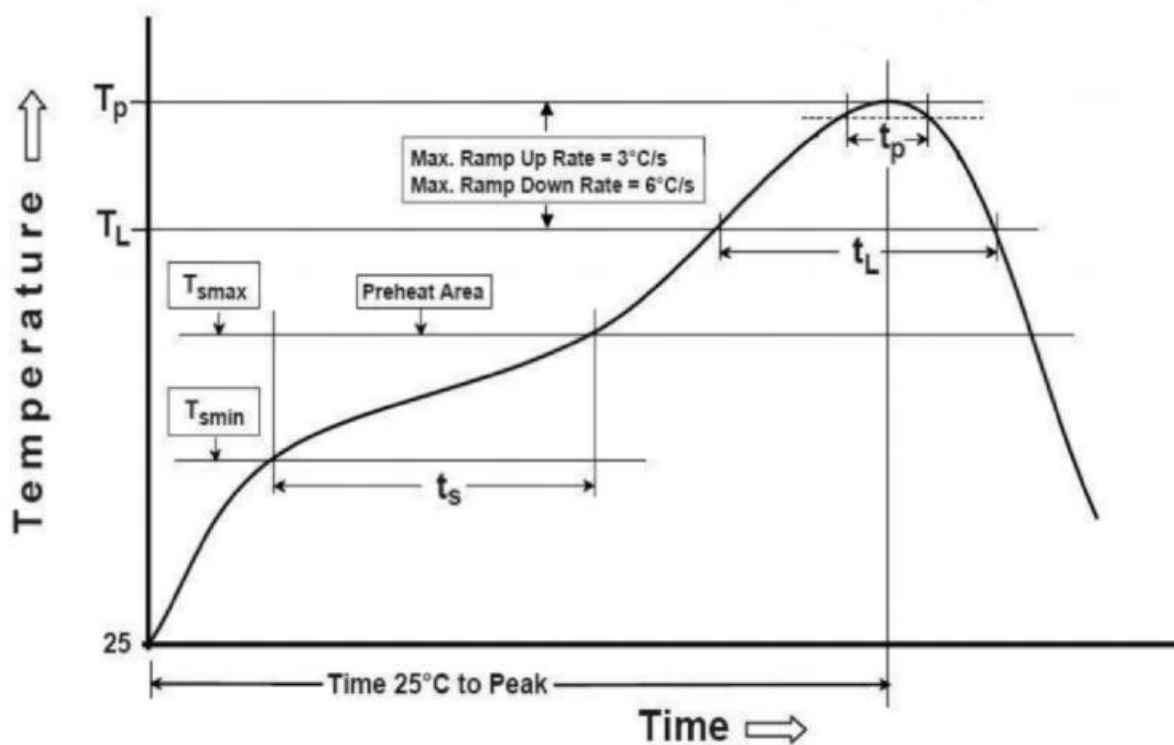
产品结构



印字

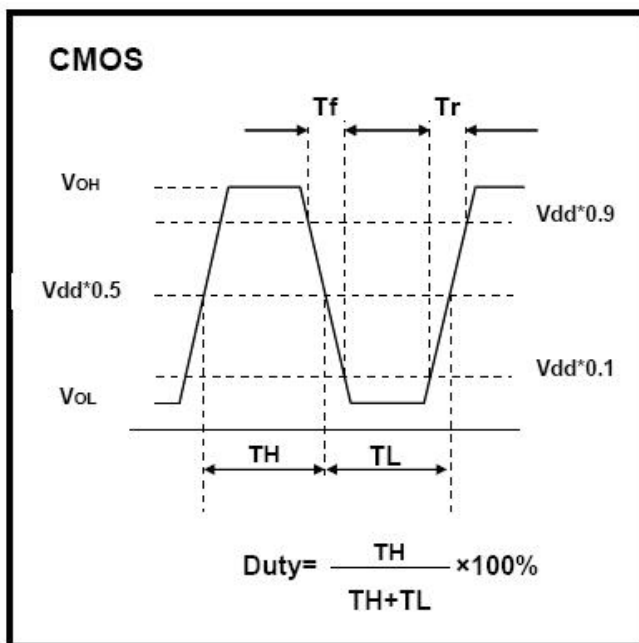
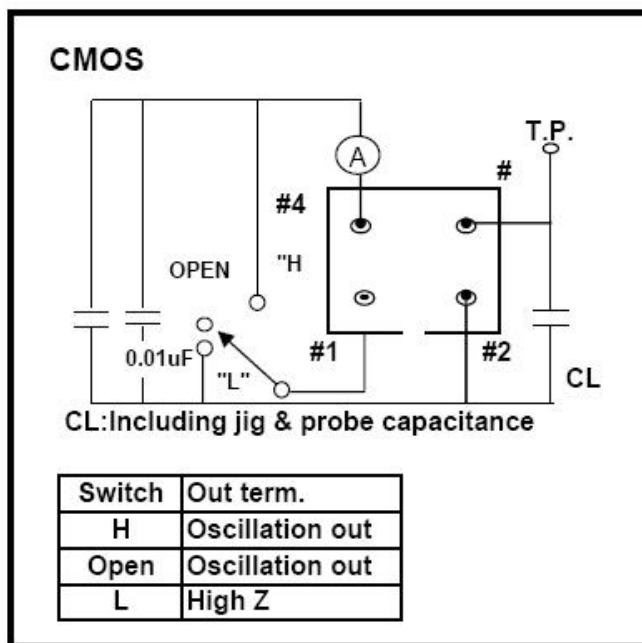


回流焊建议



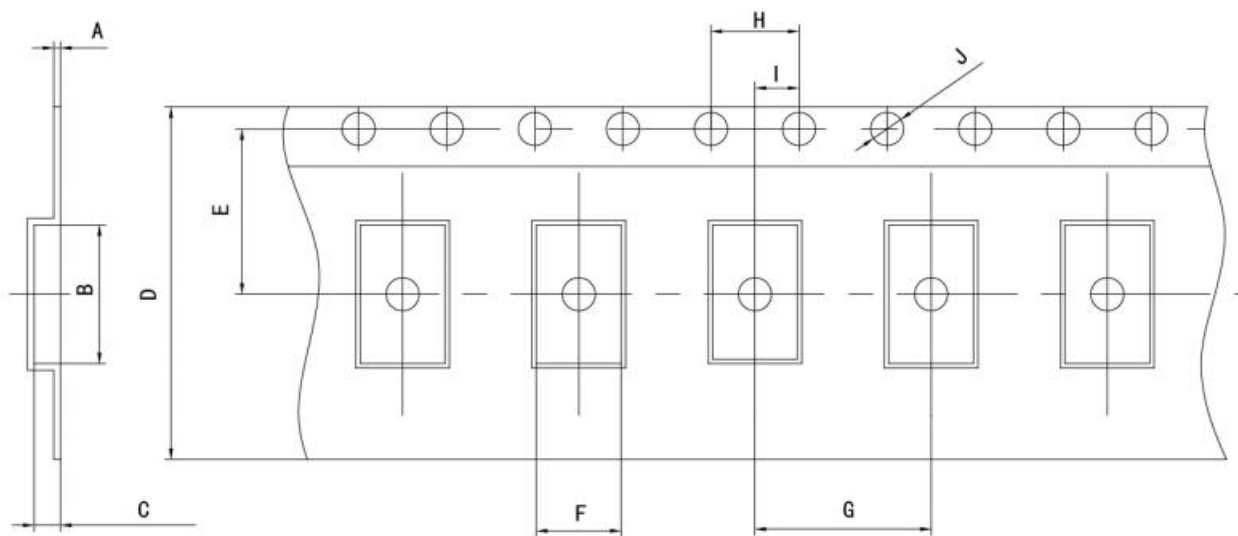
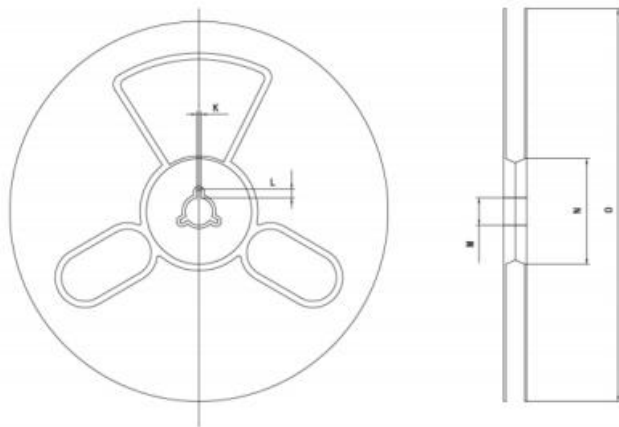
Profile Feature	Sn - Pb Eutectic Assembly	Preheat / Soak
Preheat / Soak ● Temperature Min (Ts min) ● Temperature Max (Ts max) ● Time (Ts min to Ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-120 seconds
Ramp - up rate (TL to Tp)	3°C/ second max.	3°C/ second max.
Time maintained above ● Liquidous temperature (TL) ● Time (tL) maintained above TL	183°C 60-150 seconds	217°C 60-150 seconds
Peak package body temperature (Tp)	235°C	260°C
Time within 5° C of the specified classification temperature (Tp)	20 seconds	30 seconds
Ramp - down rate (Tp to TL)	6°C/ second max.	6°C/ second max.
Time 25° C to peak temperature	6 minutes max.	8 minutes max.
Suggest reflow times	2 Times max.	

测试电路 输出波形



包装信息

T=卷带 (每卷3000/pcs)



卷带尺寸

A	B	C	D	E	F	G	H	I	J	K	L	M	N	O
0.25±0.05	3.5±0.1	1.4±0.1	8.0±0.1	3.5±0.1	2.70±0.1	4.0±0.1	4.0±0.1	2.0±0.1	φ1.5±0.1	2.0±0.2	4.0±1.0	φ13±0.5	φ60±1	φ180±1